L Number	Hits	Search Text	DB	Time stamp
1	20338	(photosensitive (photo adj3 sensitive)) with (pi polymer (photo with PI) epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 00:51
2	319867	wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 00:51
3	2330202	semiconductor chip die ic (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 00:51
4	61855	pad and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 00:52
5	120	((photosensitive (photo adj3 sensitive)) with (pi polymer (photo with PI) epoxy)) and wafer and (semiconductor chip die ic (integrated adj circuit)) and (pad and (bump ball)) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/25 00:52